

## Dual N-Ch 20V Fast Switching MOSFETs

### General Description

The QM2520C1 is the highest performance trench N-ch MOSFETs with extreme high cell density, which provide excellent R<sub>DS(on)</sub> and gate charge for most of the small power switching and load switch applications.

The QM2520C1 meet the RoHS and Green Product requirement with full function reliability approved.

### Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent C<sub>dv/dt</sub> effect decline
- Green Device Available

### Absolute Maximum Ratings

| Symbol                               | Parameter   | Rating     | Units |
|--------------------------------------|---|------------|-------|
| V <sub>DS</sub>                      | Drain-Source Voltage  | 20         | V     |
| V <sub>GS</sub>                      | Gate-Source Voltage   | ±8         | V     |
| I <sub>D</sub> @T <sub>A</sub> =25°C | Continuous Drain Current, V <sub>GS</sub> @ 4.5V <sup>1</sup> | 1.4        | A     |
| I <sub>D</sub> @T <sub>A</sub> =70°C | Continuous Drain Current, V <sub>GS</sub> @ 4.5V <sup>1</sup> | 1.1        | A     |
| I <sub>DM</sub>                      | Pulsed Drain Current <sup>2</sup>                             | 7.2        | A     |
| P <sub>D</sub> @T <sub>A</sub> =25°C | Total Power Dissipation <sup>3</sup>                          | 0.33       | W     |
| T <sub>STG</sub>                     | Storage Temperature Range                                     | -55 to 150 | °C    |
| T <sub>J</sub>                       | Operating Junction Temperature Range                          | -55 to 150 | °C    |

### Thermal Data

| Symbol           | Parameter  | Typ. | Max. | Unit |
|------------------|--|------|------|------|
| R <sub>θJA</sub> | Thermal Resistance Junction-ambient <sup>1</sup> | ---  | 375  | °C/W |
| R <sub>θJC</sub> | Thermal Resistance Junction-Case <sup>1</sup>    | ---  | 240  | °C/W |

### Product Summary

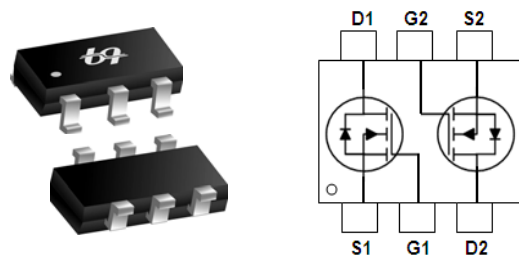


| BVDSS | R <sub>DS(on)</sub> | I <sub>D</sub> |
|-------|---------------------|----------------|
| 20V   | 115mΩ               | 1.4 A          |

### Applications

- High Frequency Point-of-Load Synchronous Small power switching for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

### SOT363 Pin Configuration



### Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

| Symbol                       | Parameter                                      | Conditions   | Min. | Typ. | Max.      | Unit                 |
|------------------------------|--|--|------|------|-----------|----------------------|
| $BV_{DSS}$                   | Drain-Source Breakdown Voltage                 | $V_{GS}=0V, I_D=250\mu A$                          | 20   | ---  | ---       | V                    |
| $\Delta BV_{DSS}/\Delta T_J$ | BVDSS Temperature Coefficient                  | Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$ | ---  | 0.02 | ---       | V/ $^\circ\text{C}$  |
| $R_{DS(ON)}$                 | Static Drain-Source On-Resistance <sup>2</sup> | $V_{GS}=4.5V, I_D=1.5A$                            | ---  | 95   | 115       | m $\Omega$           |
|                              |  | $V_{GS}=2.5V, I_D=1A$                              | ---  | 115  | 145       |                      |
|                              |  | $V_{GS}=1.8V, I_D=0.8A$                            | ---  | 140  | 175       |                      |
| $V_{GS(th)}$                 | Gate Threshold Voltage                         | $V_{GS}=V_{DS}, I_D=250\mu A$                      | 0.3  | 0.6  | 1         | V                    |
| $\Delta V_{GS(th)}$          | $V_{GS(th)}$ Temperature Coefficient           |  | ---  | -2.5 | ---       | mV/ $^\circ\text{C}$ |
| $I_{DSS}$                    | Drain-Source Leakage Current                   | $V_{DS}=16V, V_{GS}=0V, T_J=25^\circ\text{C}$      | ---  | ---  | 1         | $\mu A$              |
|                              |  | $V_{DS}=16V, V_{GS}=0V, T_J=55^\circ\text{C}$      | ---  | ---  | 5         |                      |
| $I_{GSS}$                    | Gate-Source Leakage Current                    | $V_{GS}=\pm 8V, V_{DS}=0V$                         | ---  | ---  | $\pm 100$ | nA                   |
| gfs                          | Forward Transconductance                       | $V_{DS}=5V, I_D=2A$                                | ---  | 6    | ---       | S                    |
| $R_g$                        | Gate Resistance                                | $V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$              | ---  | 2    | 4         | $\Omega$             |
| $Q_g$                        | Total Gate Charge (4.5V)                       | $V_{DS}=15V, V_{GS}=4.5V, I_D=2A$                  | ---  | 3.3  | 4.6       | nC                   |
| $Q_{gs}$                     | Gate-Source Charge                             |  | ---  | 0.51 | 0.7       |                      |
| $Q_{gd}$                     | Gate-Drain Charge                              |  | ---  | 0.88 | 1.2       |                      |
| $T_{d(on)}$                  | Turn-On Delay Time                             | $V_{DD}=10V, V_{GS}=4.5V, R_G=3.3\Omega, I_D=2A$   | ---  | 2    | 4.0       | ns                   |
| $T_r$                        | Rise Time                                      |  | ---  | 29.2 | 53        |                      |
| $T_{d(off)}$                 | Turn-Off Delay Time                            |  | ---  | 10   | 20        |                      |
| $T_f$                        | Fall Time                                      |  | ---  | 6.8  | 13.6      |                      |
| $C_{iss}$                    | Input Capacitance                              | $V_{DS}=15V, V_{GS}=0V, f=1\text{MHz}$             | ---  | 204  | 286       | pF                   |
| $C_{oss}$                    | Output Capacitance                             |  | ---  | 43.6 | 61        |                      |
| $C_{rss}$                    | Reverse Transfer Capacitance                   |  | ---  | 30   | 42        |                      |

### Diode Characteristics

| Symbol   | Parameter                                | Conditions                                       | Min. | Typ. | Max. | Unit |
|----------|--|--|------|------|------|------|
| $I_S$    | Continuous Source Current <sup>1,4</sup> | $V_G=V_D=0V$ , Force Current                     | ---  | ---  | 1.4  | A    |
| $I_{SM}$ | Pulsed Source Current <sup>2,4</sup>     |  | ---  | ---  | 7.2  | A    |
| $V_{SD}$ | Diode Forward Voltage <sup>2</sup>       | $V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$        | ---  | ---  | 1.2  | V    |
| $t_{rr}$ | Reverse Recovery Time                    | $I_F=2A, di/dt=100A/\mu s, T_J=25^\circ\text{C}$ | ---  | 3.9  | ---  | nS   |
| $Q_{rr}$ | Reverse Recovery Charge                  |  | ---  | 1.04 | ---  | nC   |

Note :

1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.

2.The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$

3.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature

4.The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.

## Dual N-Ch 20V Fast Switching MOSFETs

### Typical Characteristics

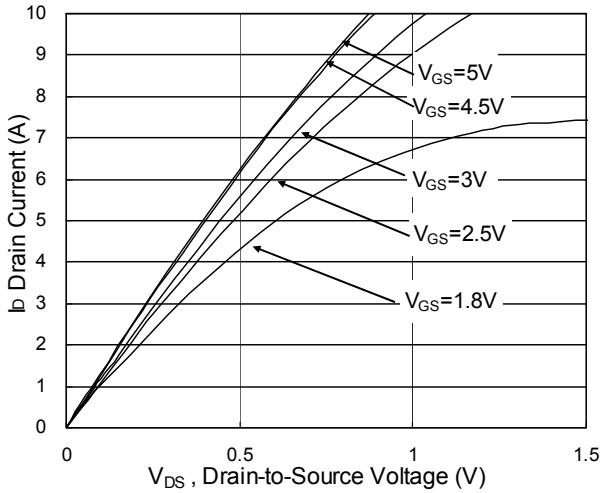


Fig.1 Typical Output Characteristics

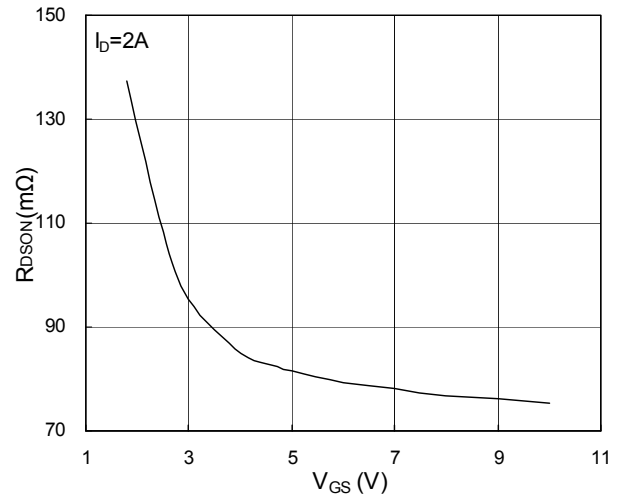


Fig.2 On-Resistance vs. Gate-Source

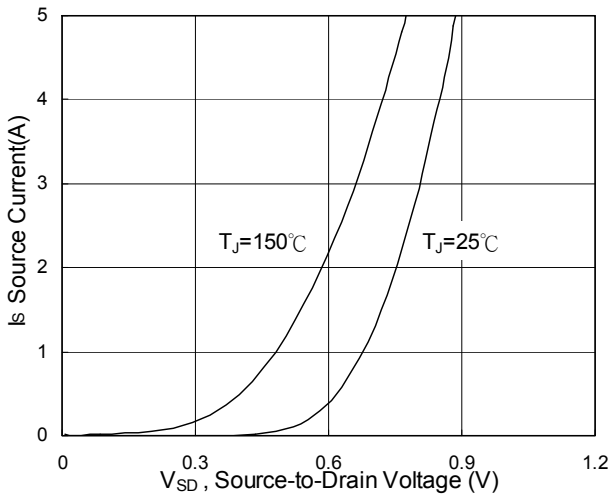


Fig.3 Forward Characteristics Of Reverse

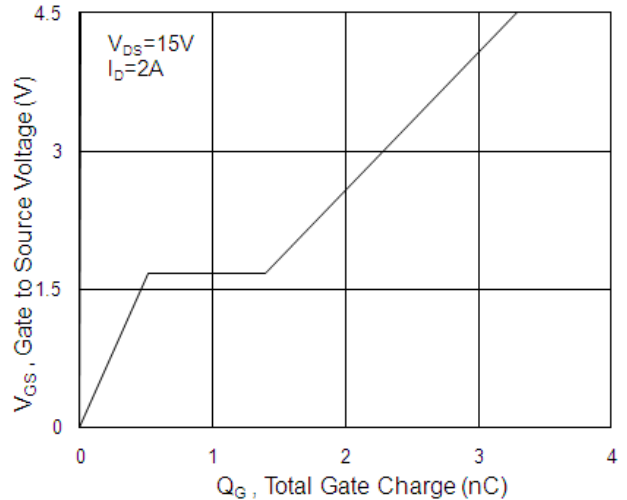


Fig.4 Gate-Charge Characteristics

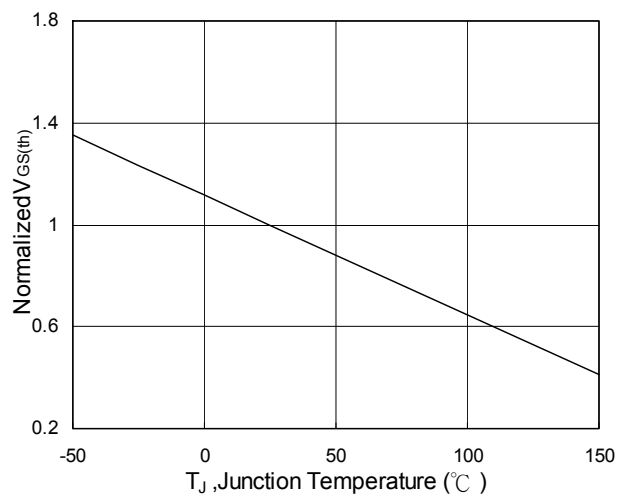


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

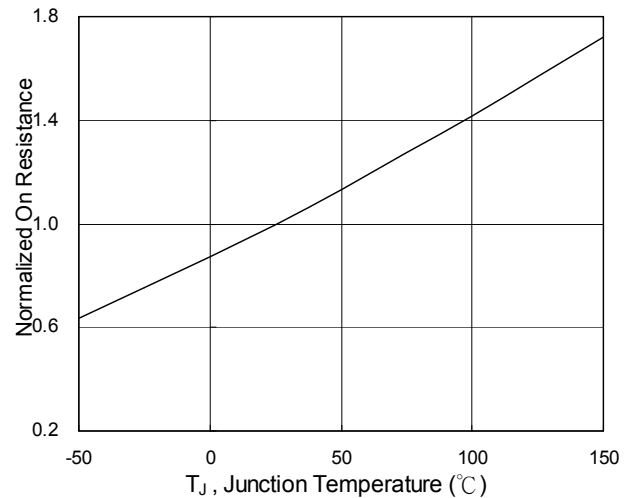


Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$

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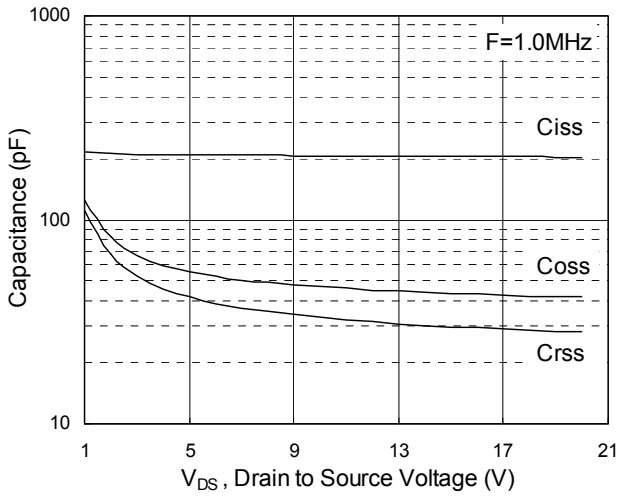


Fig.7 Capacitance

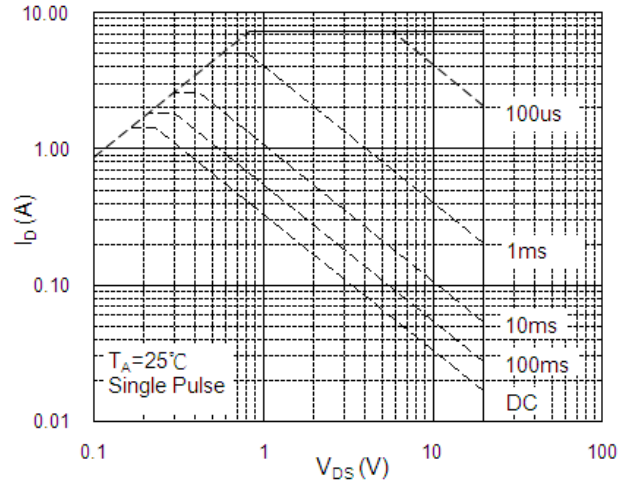


Fig.8 Safe Operating Area

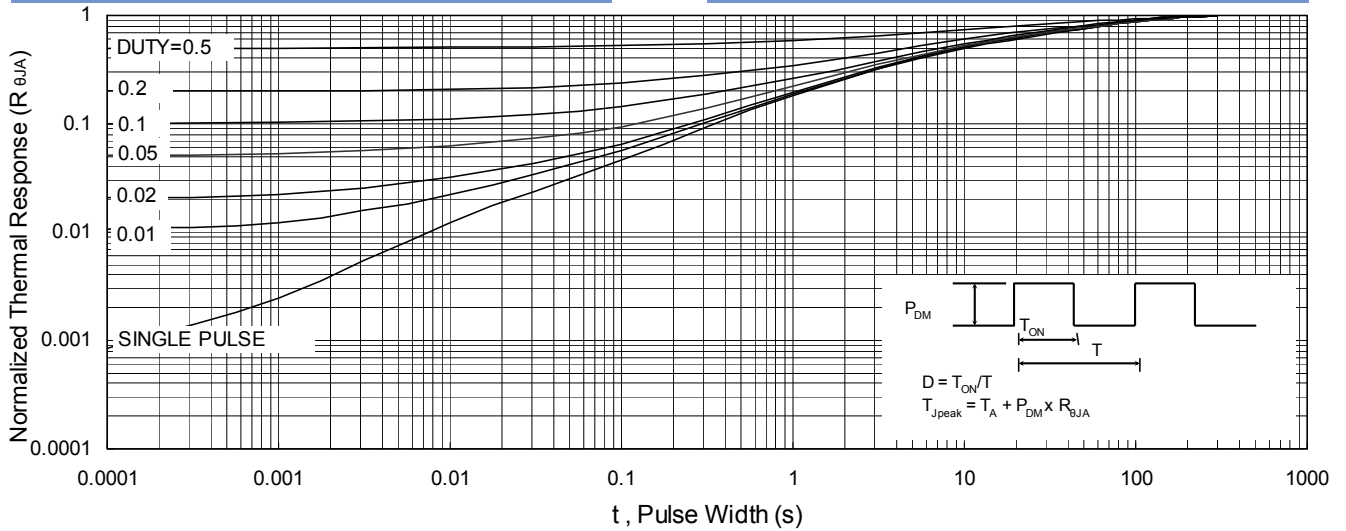


Fig.9 Normalized Maximum Transient Thermal Impedance

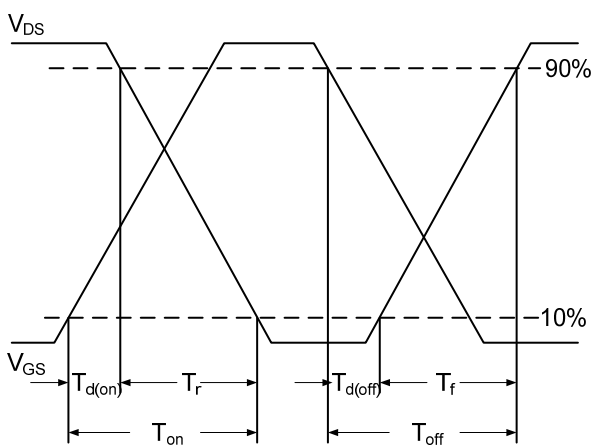


Fig.10 Switching Time Waveform

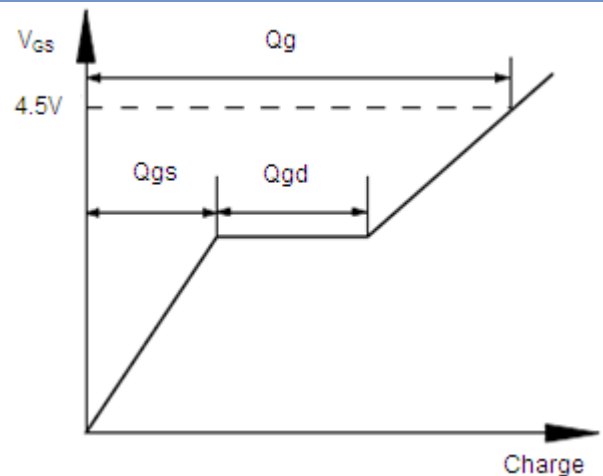


Fig.11 Gate Charge Waveform

